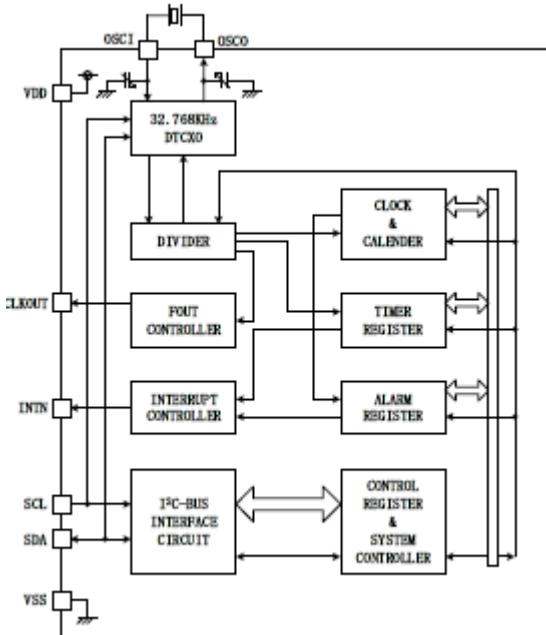


High-stability real-time clock chip with the I²C bus communication interface and the temperature compensation functions

- With the built-in 32.768KHz crystal oscillator temperature compensation circuit provides high-accuracy clock output within the scope of -40°C~85°C
- With the built-in crystal oscillator load capacitor, it supports the crystal oscillator frequency adjustment function
- It supports the high-speed I²C bus protocol (400KHz)
- Multiple interruption functions: including timing alarm interruption (settable parameters: week, day, hour, minute), fixed period interruption and time updating interruption
- Programming realization of 32.768KHz/1024Hz/1Hz clock output
- It supports complete calendar functions during 2000-2099, and supports automatic adjustment of leap year
- I²C working voltage scope: 2.0V~5.5V; clock circuit working voltage scope: 1.6V~5.5V
- Low current power consumption: [2.3μA@3V\(Typ\)](#)

■ Structure diagram

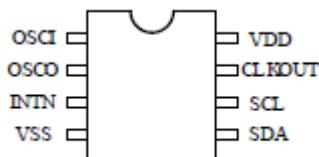


■ General specifications

- Highly frequency stability:**
 - 25°C:±20ppm; (monthly deviation less than 55s)
 - 40~85°C:±50ppm; (monthly deviation less than 136s)
- Built-in 12.5pF crystal load capacitor, in no need of calibration for output frequency**
- Can slightly adjust the frequency through the configuration register: (0.75ppm/Step)**
- Programmable to realize different frequency output functions:**
 - CLKOUT pin can drive 30pF capacitor load
 - Optional output frequency: 32.768kHz, 1024Hz, 1Hz
- Abundant interruption functions:**
 - Fixed period interruption: set any period interruption between 1/4096s and 4095
 - Timing alarm interruption: Can generate alarm interruption events in set week, day, hour or minute.
 - Time updating interruption: Generate interruption alarm events with second updating or minute updating according to the set value.
 - Automatic leap year adjustment function

■ Definitions of pins

Pin No.	Pin Name	Function
1	OSCI	Crystal oscillator input
2	OSCO	Crystal oscillator output
3	INTN	Interruption output port, N_Ch leakage structure
4	VSS	Ground circuit
5	SDA	I ² C bus communication data transmission end
6	SCL	I ² C bus communication serial clock input end
7	CLKOUT	Clock output end and CMOS output
8	VDD	Power supply

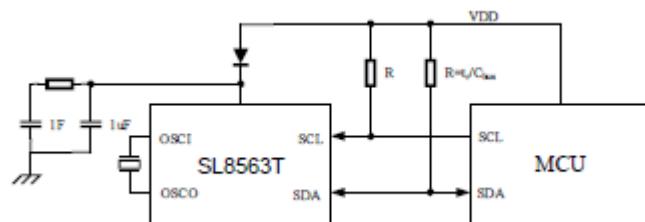


■ Electrical characteristics

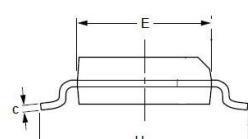
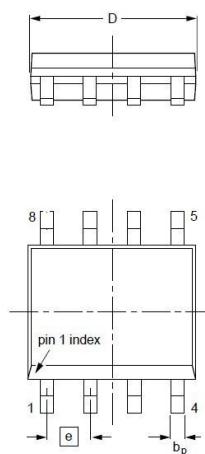
*Please refer to the User Guide for detailed data

Item	Symbol	Condition		Min.	Typ.	Max.	Unit
Current power consumption	IDD1	Disable CLKOUT	V _{DD} =3V		2.3	2.6	μA
	IDD2		V _{DD} =5V		2.4	2.7	
	IDD3	CLKOUT=32.768KHz	V _{DD} =3V		2.9	3.3	
	IDD4		V _{DD} =5V		3.6	4.0	
Low level input voltage	V _{IL}	SCL, SDA Pins		0		0.3V _{DD}	V
High level input voltage	V _{IH}			0.7V _{DD}		V _{DD}	
Low level output voltage	V _{OL}	FOUT, INTN, SDA pins	I _{OH} =-1mA	0		0.3	V
High level output voltage	V _{OH}	FOUT pin	I _{OL} =1mA	V _{DD} -0.3		V _{DD}	
SCL clock period	f _{SCL}	V _{DD} =2.0V~5.5V				400	KHz
CLKOUT duty ratio	δ _{CLKOUT}	V _{DD} =1.6V~5.5V			50		%
CLKOUT voltage coefficient	Δf/f	V _{DD} =2.0V~5.5V				1.0	ppm/V
Crystal ESR	R _s					70	KΩ
Crystal shunt load capacitor	C _L				12.5		pF

■ Application cases



■ Package Specification



	A	A ₁	A ₂	A ₃	b _p	c	θ	UNIT
MAX	1.8	0.3	1.45		0.49	0.3	8°	mm
TYP				0.3				
MIN		0.1	1.25		0.36	0.2	0°	
	D	E	e	H _E	L	L _p	Q	UNIT
MAX	5.0	4.0		6.2		1.0	0.7	mm
TYP	4.9	3.9	1.27	6.0	1.05			
MIN	4.8	3.8		5.8		0.4	0.6	

